



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



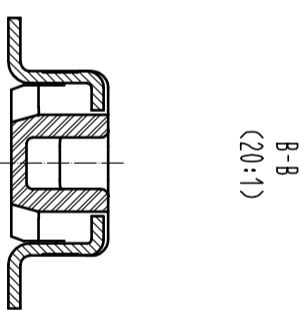
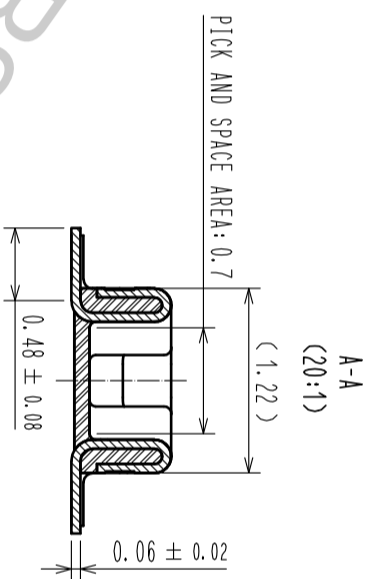
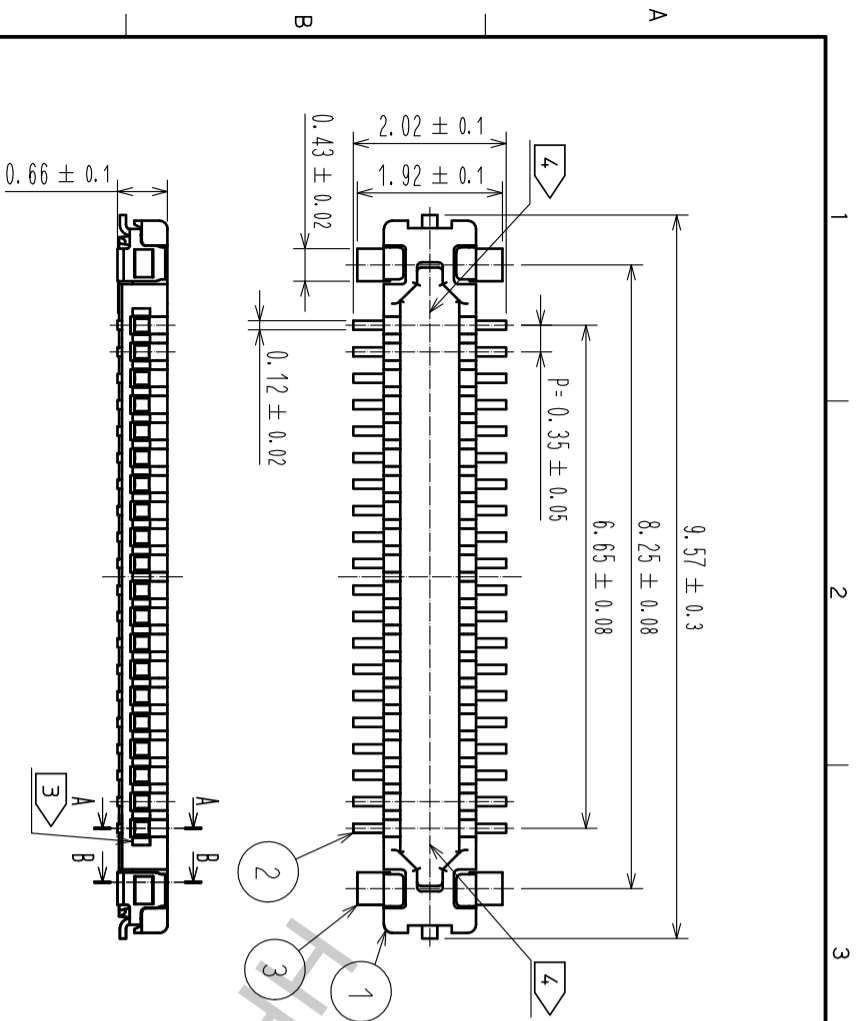
Contact us

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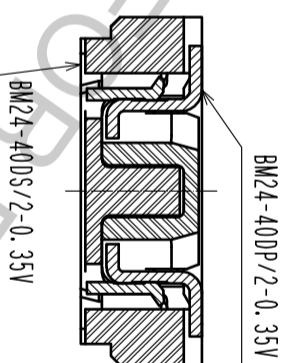
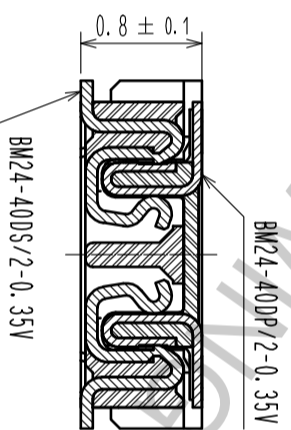
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



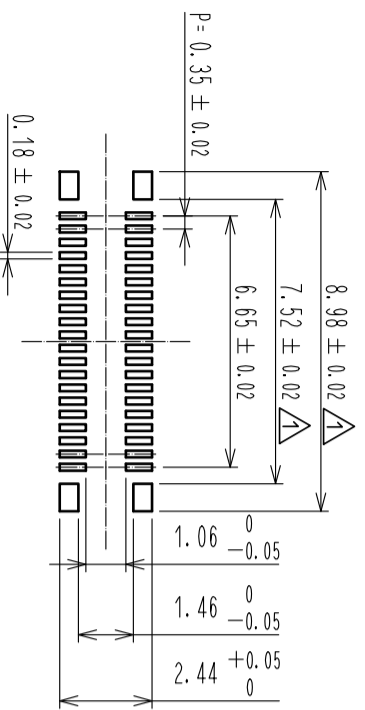


ENGAGEMENT FIGURE (20:1)

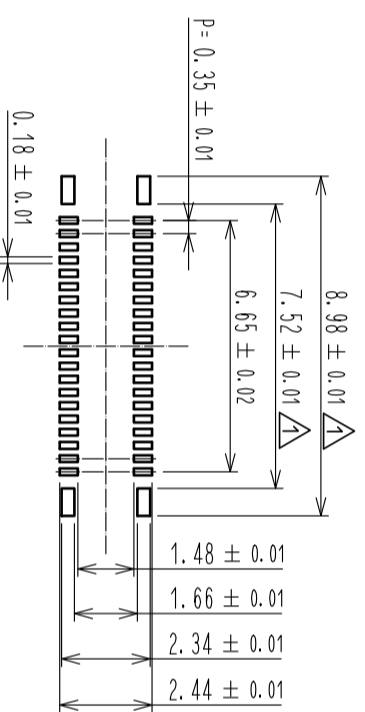
- NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
- 2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
UNDER PLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 3 A PART OF THE WALL COULD BE NOTCHED.
 - 4 HRS MARK AND CAV No. ARE INDICATED IN APPROX. POSITION SHOWN.



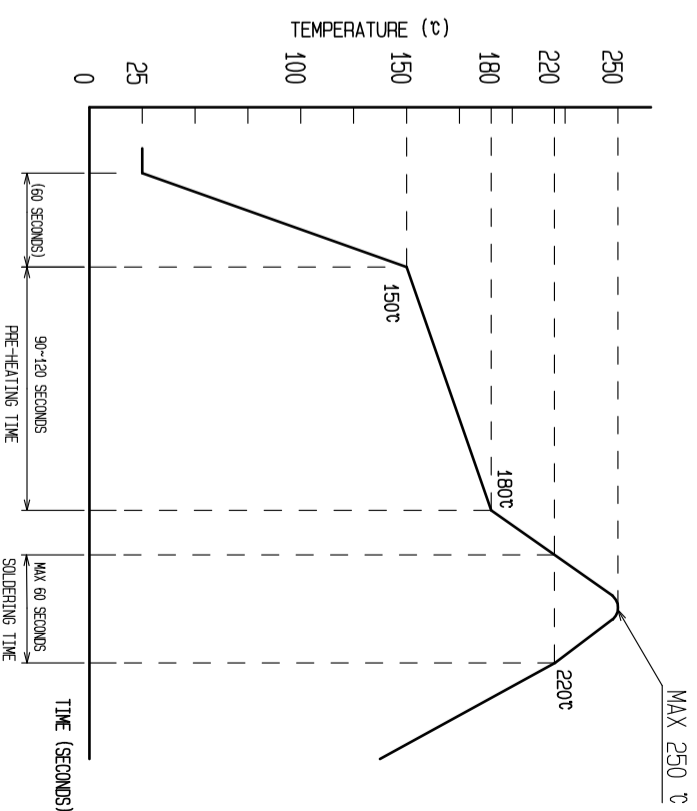
◆ RECOMMENDED PCB LAYOUT



◆ RECOMMENDED METAL MASK DIMENSIONS
METAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS
FROM OUR RECOMMENDATION.

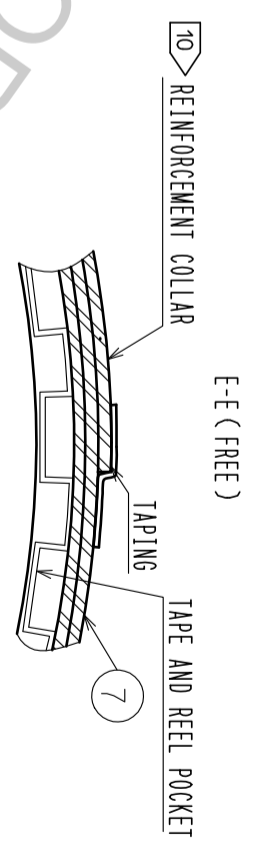
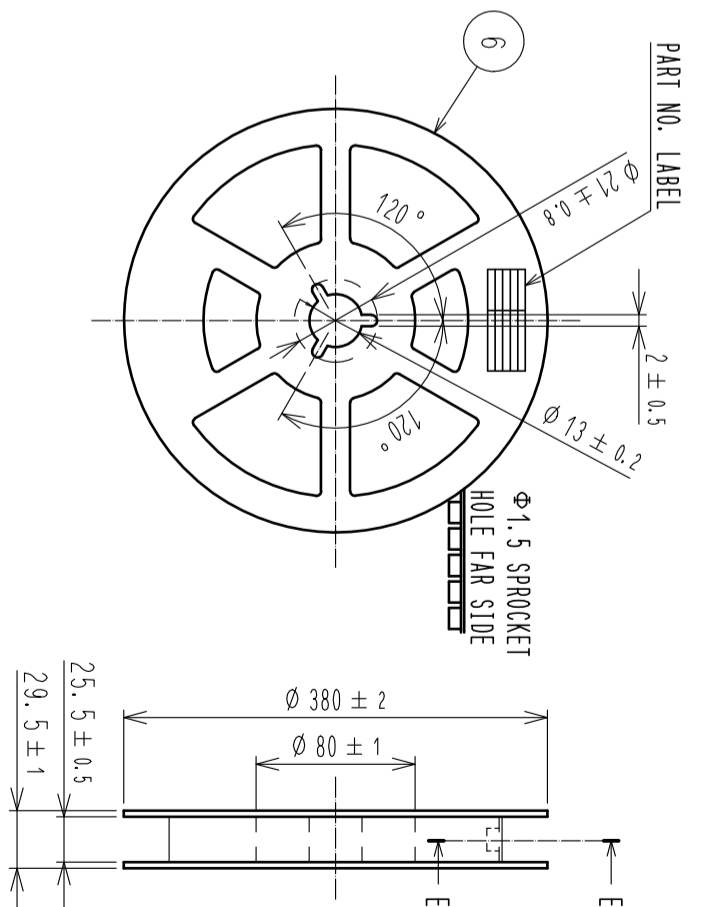
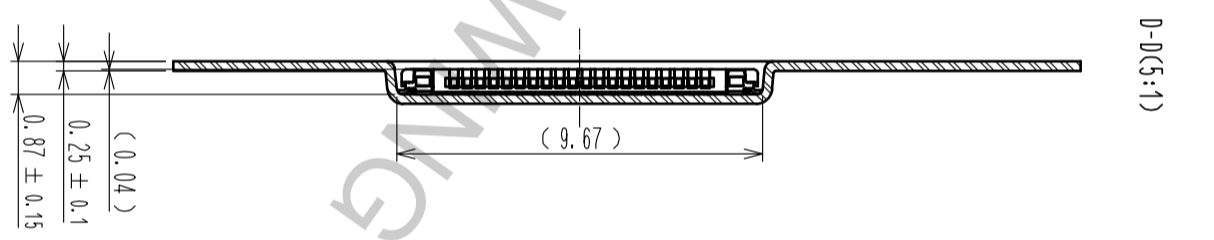
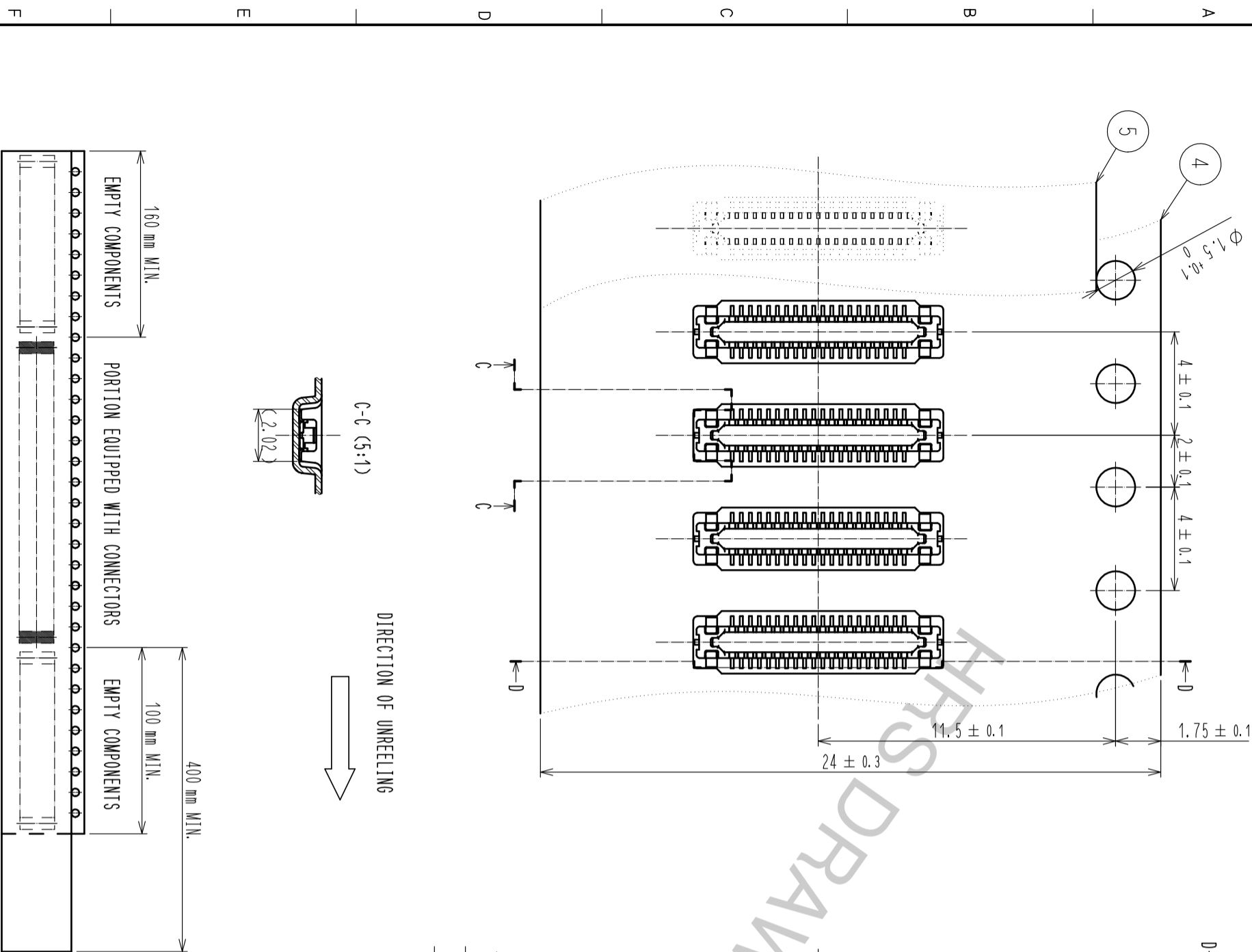
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
4	PS	CLEAR	EMBOSSED CARRIER TAPE)	7	PS	CLEAR	(REINFORCEMENT COLLAR)
3	COPPER ALLOY	2		6	PS	BLACK	(PLASTIC REEL)
2	PHOSPHOR BRONZE	2		5	POLYESTER	CLEAR	(COVER TAPE)
1	LCP	UL94 V-0.	BLACK				

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10 : 1	4	DIS-H-00001151	NY. YAMASHIRO	TS. MIYAZAKI	15.12.03

APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE
KH. IKEDA	WR. FUKUCHI	YH. HASEGAWA	YH. HASEGAWA	EDC-357613-51-01	BM24-400P/2-0.35V(51)	CL677-2009-0-51

EMBOSSED CARRIER TAPE PACKAGING (FREE)

STYLE AND DIMENTION OF REEL (FREE)



DETAIL OF PART NO. LABEL

製造年月日	*** **	DATA OF MANUFACTURED
製品コード	CL677-2009-0(51)	CODE NO.
製品名	BM24-40DP/2-0.35V(51)	PART NO.
数量	10,000	QUANTITY
納入者	ヒロセ電機(株)	SUPPLIER

- 7 . PER REEL 10,000 CONNECTORS.
- 8 . THE DIMENSIONS IN PARENTHESSES ARE FOR REFERENCE.
- 9 . REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 10 . AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

TRAILER

9 TAPING(FREE)

LEADER

